

LINEAR TECHNOLOGY MATERIALS DECLARATION

| 1t1632is8#trpbf                   |                                  |                           |            | (Engineering Calculation) |                               | SOIC                            |
|-----------------------------------|----------------------------------|---------------------------|------------|---------------------------|-------------------------------|---------------------------------|
| (printed on: 2020-07-11 16:25:16) |                                  |                           |            |                           | TOTAL MASS (g) : 0.076307     |                                 |
| COMPONENT MATERIAL                | VENDOR/ INDUSTRY NAMES           | CONSTITUENT NAME          | CAS NUMBER | CONSTITUENT MASS (g)      | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. |
| Active Device                     | Linear Technology                | Silicon (Si)              | 7440-21-3  | 0.004397                  | 1000000                       | 57622.6171875                   |
| Die Coat                          | Dow Corning                      | Silicone                  | 69430-27-9 | 0.000183                  | 1000000                       | 2398.21191406                   |
| Lead Frame                        | Cu                               | Copper (Cu)               | 7440-50-8  | 0.023653                  | 975000                        | 309972.15625                    |
|                                   |                                  | Iron (Fe)                 | 7439-89-6  | 0.000582                  | 24000                         | 7627.10009766                   |
|                                   |                                  | Phosphorus (P)            | 7723-14-0  | 0.000007                  | 300                           | 91.7348861694                   |
|                                   |                                  | Zinc (Zn)                 | 7440-66-6  | 0.000017                  | 700                           | 222.784729004                   |
|                                   |                                  | Nickel (Ni)               | 7440-02-0  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Silicon (Si)              | 7440-21-3  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Magnesium (Mg)            | 7439-95-4  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Tin (Sn)                  | 7440-31-5  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Lead Frame Total:         |            | 0.024259                  | 1000000                       | 317913.78125                    |
| Plating                           | PMI                              | Exter. Plating Pb         | 7439-92-1  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Exter. Plating Sn         | 7440-31-5  | 0.001477                  | 1000000                       | 19354.1210938                   |
|                                   |                                  | External Plating Total:   |            | 0.001477                  | 1000000                       | 19354.1210938                   |
|                                   |                                  | Inter. Plating Ni         | 7440-02-0  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Inter. Plating Ag         | 7440-22-4  | 0.000194                  | 1000000                       | 2542.36669922                   |
|                                   |                                  | Internal Plating Total:   |            | 0.000194                  | 1000000                       | 2542.36669922                   |
| Die Attach                        | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag)               | 7440-22-4  | 0.001189                  | 750000                        | 15581.8251953                   |
|                                   |                                  | Tin (Sn)                  | 7440-31-5  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Lead (Pb)                 | 7439-92-1  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Silica (SiO2)             | 60676-86-0 | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Indium (In)               | 7440-74-6  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Metal Oxide               |            | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Antimony (Sb)             | 7440-36-0  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Resin (EP)                |            | 0.000396                  | 250000                        | 5189.57324219                   |
|                                   |                                  | Die Attach Total:         |            | 0.001585                  | 1000000                       | 20771.3984375                   |
| Encapsulation                     | MULTI-AROMATIC RESIN Br/Sb FREE  | Resin (EP)                |            | 0.006604                  | 150000                        | 86545.3125                      |
|                                   |                                  | Bromine (Br)              | 40039-93-8 | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Silica (SiO2)             | 60676-86-0 | 0.036102                  | 820000                        | 473116.125                      |
|                                   |                                  | Antimony Trioxide (Sb2O3) | 1309-64-4  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Metal Hydroxide           |            | 0.001101                  | 25000                         | 14428.5869141                   |
|                                   |                                  | Carbon Black (C)          | 1333-86-4  | 0.000220                  | 5000                          | 2883.09643555                   |
|                                   |                                  | Encapsulation Total:      |            | 0.044027                  | 1000000                       | 576973.125                      |
| Bond Wire Estimated               | AFW/TANAKA/ Kn                   | Gold (Au)                 | 7440-57-5  | 0.000185                  | 1000000                       | 2424.421875                     |
|                                   |                                  |                           |            |                           | TOTAL MASS (g) :              | 0.076307                        |